=> d his

STN SPACE JAMES JA

(FILE 'HOME' ENTERED AT 15:18:55 ON 05 JUN 2007)

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FILE 'HCAPLUS, INSPEC, JAPIO, USPATFULL, USPAT2, INPADOC' ENTERED AT
     15:19:17 ON 05 JUN 2007
           17937 S (CZ OR CZOCHARALSKI)
L1
L2
       . 565245 S (MONO OR SINGLE) (8A) (CRYSTAL#)
L3 '
           16929 S (N(W) REGION#)
            3440 S (OSF OR OXIDATION(W) INDUCED(W) STACKING(W) FAULT)
L4
L5
          122049 S (RING(W)SHAPE#)
L6
            4509 S (GAS(W)FLOW(W)RING# OR GAS(W)FLOW)(8A)(CYLINDER# OR BAFFLE#)
L7
           12076 S (200(W)MM)(8A)(DIAMETER#)
=> s 11 and 12 and 13 and 14 and 15 and 16 and 17
             10 L1 AND L2 AND L3 AND L4 AND L5 AND L6 AND L7
L8
=> d 18 1-10 abs,bib
1.8
     ANSWER 1 OF 10 USPATFULL on STN
AR
       The present invention is a method for producing a single
       crystal with pulling the single crystal from
      a raw material melt in a chamber by CZ method, wherein when
       growing the single crystal, where a pulling rate is
       defined as V and a temperature gradient of the crystal is
       defined as G during growing the single crystal, the
       temperature gradient G of the crystal is controlled by changing at least two or more of pulling conditions including a diameter
       of the straight body of the single crystal, a rotation rate of the single crystal during pulling
       the single crystal, a flow pate of an inert-gas
       introduced into the chamber / a position of a heater heating the raw
       material melt and a distance between the melt surface of the raw
       material melt and a heat insulating member provided in the chamber so as
       to oppose to the surface of the raw material melt, thereby V/G which is a ratio of the pulling rate V and the temperature gradient G of the
       crystal is controlled so that a single crystal
       including a desired defect region is grown. Thereby, there is provided a
       method for producing a single crystal in which when
       the single crystal is grown by CZ method,
       V/G can be controlled without lowering a pulling rate V, and thus the
       single crystal including a desired defect region can
       be produced effectively for a short time.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
ΑN
       2007:20399 USPATFULL
TΙ
       Process for producing single crystal and
       single crystal
ΙN
       Sakurada, Masahiro, Fukushima, JAPAN
       Iida, Makoto, Fukushima, JAPAN
       Mitamura, Nobuaki, Fukushima, JAPAN
       Ozaki, Atsushi, Fukushima, JAPAN
PA
       Shin-Etsu Handotai Co., Ltd., Tokyo, JAPAN, 1000005 (non-U.S.
       corporation)
ΡI
       US 2007017433
                                 20070125
                             Α1
ΑI
       US 2004-560581
                             A1
                                  20040528 (10)
       WO 2004-JP7350
                                  20040528
                                  20060202 PCT 371 date
PRAI
       JP 2003-185773
                             20$30627
       Utility
DT
FS
       APPLICATION
LREP
       OLIFF & BERRIDGE, PLC, P.O. BOX 19928, ALEXANDRIA, VA, 22320, US
CLMN
       Number of Claims: 21
ECL
       Exemplary Claim: 1
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5 Drawing Page(s)
LN.CNT 1030
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
      ANSWER 2 OF 10 USPATFULL on STN
AB
         The present invention provides a method for producing a single
         crystal by pulling a single crystal from a
         raw material melt in a chamber in accordance with Czochralski method,
         comprising pulling a single cfystal having a
         defect-free region which is optside an OSF region to occur in
         a ring shape in the radial difrection and which
        interstitial-type and vacancy-type defects do not exist in, wherein the pulling of the single crystal is performed with
        being controlled so that an average of cooling rate in passing through a
        temperature region of the melt point of the single
        crystal to 950° C. is in the range of 0.96° C./min
        or more and so that an average of cooling rate in passing through a
        temperature region of 1150^{\circ}/\tilde{C}. to 1080^{\circ} \tilde{C}. is in the range
        of 0.88^{\circ} C./min or more and so that an average of cooling rate in
        passing through a temperature region of 1050° C. to 950°
        C. is in the range of 0.71 C./min or more. Thereby, production
        margin in pulling a single crystal having a
        defect-free region can be considerably enlarged and therefore there can
        be provided a method for producing a single crystal
        by which production yield and productivity of the crystal having the
        defect-free region can be considerably improved.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AN
        2006:318540 USPATFULL
TΙ
        Method for producing a single crystal
ΙN
        Hoshi, Ryoji, Fukushima, JAPAN
        Sonokawa, Susumu, Fukushima, JAPAN
        Shin-Etsu Handotai Co., Itd., Chiyoda-ku, JAPAN (non-U.S. corporation) US 2006272570 A1 20061207
PΑ
PΙ
ΑI
        US 2004-573822
                                     20041019 (10)
                                A1
        WO 2004-JP15395
                                     20041019
                                     20060328 PCT 371 date
PRAI
        JP 2003-369855
                                20031030
        Utility
FS
        APPLICATION
LREP
        OLIFF & BERRIDGE, PLC, P.O. BOX 19928, ALEXANDRIA, VA, 22320, US
CLMN
        Number of Claims: 17
ECL
        Exemplary Claim: 1-7
DRWN
        6 Drawing Page(s)
LN.CNT 751
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 3 OF 10 USPATFULL on STN
\Gamma8
AB
        The present invention is a method for producing a single
        crystal in accordance with Czochralski method by flowing an
        inert gas downward in a chamber 1 of a single crystal
        -pulling apparatus 11 and surroupding a single crystal
        3 pulled from a raw material mert 2 with a gas flow
        -guide cylinder 4, wherein when a single crystal within N region outside OSE region generated in a rink signal the radial direction of the pingle crystal is pulled the single crystal within N region is
        pulled in a condition at
                                       flow
                                                          the inert gas between the
        single crystal and the das flaw
-guide cylinder is 0 D(L) or more and pressure in the chamber is 0.6 D(hPa) or less, in which D (mm) is a diameter of the single crystal to be pulled. It is preferable that
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there is used the gas flow-guide cylinder

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single crystal, wherein in the case that a
       single crystal is produced by an apparatus having a
       gas flow-guide cylinder in accordance with
       CZ method, the single crystal has low defect
       density and Fe concentration can be suppressed to be 1+10.sup.10
       atoms/cm.sup.3 or less even in a peripheral part thereof.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
       2006:277991 USPATFULL
       Process for producing single crystal and silicon
       crystal wafer
       Fusegawa, Izumi, Fukushima, JAPAN
       Mitamuria, Nobuaki, Fukushima, JAPAN
       Yanagimachi, Takahiro, Fukushima, JAPAN
       Shin-Etsu Handotai Co., Ltd., Chiyoda-ku, JAPAN (non-U.S. corporation)
                           A1
       US 2006236919
                               20061026
                           A1 20040813 (10)
     US 2004-568186
       WO 2004-JP11685
                               20040813
                               20060303 PCT 371 date
       JP 2003-296837
                           20030820
       Utility
       APPLICATION
       OLIFF & BERRIDGE, PLC, P.O. BOX 19928, ALEXANDRIA, VA, 22320, US
       Number of Claims: 18
       Exemplary Claim: 1-6
       5 Drawing Page(s)
LN.CNT 631
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 4 OF 10 USPATFULL on STN
       The present invention is a method for producing a single
       crystal of which a whole plane in a radial direction is a
       defect-free region with pulling the s‡ngle crystal
       from a raw material melt in a chamber/by Czochralski method, wherein a
       pulling condition is changed in a diffection of the crystal
       growth axis during pulling the single crystal so
       that a margin of a pulling rate is a A ways a predetermined value or more
       that the single crystal of which the whole plane in
       a radial direction is a defect-free region can be pulled. Thereby, there
       can be provided a method for producting a single
       crystal in which when a single crystal is
      produced by CZ method, the single/crystal
       of which a whole plane in a radial direction is a defect-free region
       entirely in a direction of the c\sharpystal growth axis can be produced with
       stability.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
       2006:205843 USPATFULL
      Method for producing single crystal and
       single crystal
      Mitamura, Nobuaki, Fukushima, JAPAN
      Ohta, Tomohiko, Gunma, JAPAN
       Fusegawa, Izumi, Fukushima, JAPAN
       Sakurada, Masahiro, Fukushima, JAPAN
      Ozaki, Atsushi, Fukushima, JAPAN
       SHIN-ETSU HANDOTAI CO., LTD., Tokyo, JAPAN (non-U.S. corporation)
                           A1 20060810
      US 2006174819
      US 7226507
                           B2 20076605
      US 2004-561865
                               2004/0527 (10)
                           A1
      WO 2004-JP7252
                               2004/0527
                               20060220 PCT 371 date
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that Fe concentration is 0.05 ppm or less, at least, in a surface thereof. Thereby, there is provided a method for producing a

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PRAI

JP 2003-184838

2003062**/**7

DΤ

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DT
        Utility
FS
        APPLICATION
        OLIFF & BERRIDGE, PLC, P.O. BOX 19928 ALEXANDRIA, VA, 22320, US
LREP
CLMN
        Number of Claims: 21
        Exemplary Claim: 1-11
ECL
DRWN
        9 Drawing Page(s)
LN.CNT 1041
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
      ANSWER 5 OF 10 USPATFULL on STN
L8
AΒ
        The present invention is a method for producing a single
        crystal with pulling the single crystal from
        a raw material melt by CZ method, wherein when growing the
        single crystal, where a pulling rate is defined as V, a temperature gradient of the crystal at a central portion of the
        crystal is defined as Gc, and a temperature gradient of the crystal at a
        peripheral portion of the crystal is defined as Ge, the temperature
        gradient Gc at the central portion of the crystal and the temperature
        gradient Ge at the peripheral portion of the crystal are controlled by
        changing a distance between the melt surface of the raw material melt and a heat insulating member provided so as to oppose to the surface of
        the raw material melt, thereby difference \Delta G between the
        temperature gradient Gc at the central portion of the crystal and the
        temperature gradient Ge at the peripheral portion of the crystal is
        0.5° C./mm or less, and also V/Gc which is a ratio of the pulling
        rate V and the temperature gradient Cc at the central portion of the
        crystal is controlled so that a sindle crystal
        including a desired defect region can be grown. Thereby, there is
        provided a method for producing a single crystal in
        which when the single crystal is grown by CZ
       method, V/G can be controlled with\phiut lowering the pulling rate V, and
        thus the single crystal including \mbox{\mbox{\mbox{$4$}}} desired defect
        region over a whole plane in the radial direction entirely in the
        direction of the crystal growth axis can be produced effectively for a
        short time and at high yield.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
ΑN
        2006:155224 USPATFULL
TI
        Process for producing single crystal and
        single crystal
ΙN
       Sakurada, Masahiro, Fukushima, JAPAN
PΙ
       US 2006130740
                            A1 20060622
ΑI
       US 2004-561205
                                 20040528 (10)
       WO 2004-JP7349
                                 20040528
                                 20060203/ PCT 371 date
PRAI
       JP 2003-185960
                             20030627
DT
       Utility
FS
       APPLICATION
·LREP
       OLIFF & BERRIDGE, PLC, P.O. BOX 19928, ALEXANDRIA, VA, 22320, US
CLMN
       Number of Claims: 49
ECL
       Exemplary Claim: 1-9
DRWN
        5 Drawing Page(s)
LN.CNT 1249
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 6 OF 10 USPATFULL on STN
r_8
AΒ
       There are disclosed a silicon wafer for epitaxial growth wherein the
       wafer is produced by slicing a silicon single crystal
       grown with doping nitrogen accordi#g to the Czochralski method (
       CZ method) in the region where at least the center of the wafer
       becomes V region in which the void type defects are generated, and
       wherein the number of defects having an opening size of 20 nm or less
       among the void type defects appearling on the surface of the wafer is
       0.02/cm.sup.2 or less, and an epitalial wafer wherein an epitaxial layer
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wherein very few SF exist in the epitaxial layer easily at high
        productivity and at low cost.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
ΆN
        2005:243977 USPATFULL
ΤI
        Silicon wafer for epitaxial growth, ppitaxial wafer, and its
        manufacturing method
TN
        Hoshi, Ryoji, Fukushima, JAPAN
        Sonokawa, Susumu, Fukushima, JAPAN
PA
        Shin-Etsu Handotai Co., Ltd., Tokyd, JAPAN (non-U.S. corporation)
PΤ
        US 2005211158
                              A1
                                  20050929
        US 7204881
                              В2
                                  20070417
AΤ
        US 2003-520099
                                  20030708
                                            (10)
        WO 2003-JP8671
                                  20030708
                                  20050104
                                             PCT 371 date
PRAI
        JP 2002-204703
                              20020712
DΤ
        Utility
FS
        APPLICATION
        OLIFF & BERRIDGE, PLC, P.O. BOX 19928, ALEXANDRIA, VA, 22320, US
LREP
CLMN
        Number of Claims: 30
ECL
        Exemplary Claim: 1-11
DRWN
        6 Drawing Page(s)
LN.CNT 849
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
\Gamma8
     ANSWER 7 OF 10 USPATFULL on STN
AB
        The present invention provides a silicon wafer sliced from a silicon
        single crystal ingot grown by the Czoch alski method
        under such conditions that V-rich regio\hbar should become dominant, wherein
        count number of particles having a size of 0.1 \mum or more is 1
       count/cm.sup.2 or less when particles are counted by using a particle counter and a method for producing a slicon single
        crystal. Thus, there is provided a production technique that can
       improve productivity and reduce cost for high quality silicon wafers of excellent device characteristics by farther reducing density and size of
       defects such as COP.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AN
        2002:284777 USPATFULL
TI
       Silicon wafer and method for producing silicon single
       crystal
ΤN
       Hoshi, Ryoji, Fukushima, JAPAN
       Fusegawa, Izumi, Fukushima, JAPAN
       Ohta, Tomohiko, Fukushima, JAPAN
       Maeda, Shigemaru, Fukushima, JAPAN
       US 2002157598
ΡI
                             A1
                                  20021031
       US 6632411
                             ₿2
                                  20031014
ΑI
       US 2001-979519
                             Α1
                                  20011123
       WO 2001-JP2451
                                  20010327
PRAI
       JP 2000-92337
                             20000329
DT
       Utility
FS
       APPLICATION
LREP
       Oliff & Berridge, PO Box 19928, Alexandria, VA, 22320
CLMN
       Number of Claims: 9
ECL
       Exemplary Claim: 1
DRWN
       4 Drawing Page(s)
LN.CNT 705
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 8 OF 10 USPAT2 on STN
1.8
AΒ
       The present invention is a method for producing a single
       crystal of which a whole plane in a radial direction is a
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is formed on the silicon wafer for epitaxial growth. Thereby, there can

be produced an epitaxial wafer having a high gettering capability

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from a raw material melt in a chamber by Czochralski method, wherein a
       pulling condition is changed in a difection of the crystal
       growth axis during pulling the single crystal so
       that a margin of a pulling rate is a ways a predetermined value or more
       that the single crystal of which the whole plane in
       a radial direction is a defect-free region can be pulled. Thereby, there
       can be provided a method for producing a single
       crystal in which when a single crystal is
       produced by CZ method, the single drystal of which a whole plane in a radial direction is a defect-free region
       entirely in a direction of the crystal growth axis can be produced with
       stability.
CAS INDEXING IS AVAILABLE FOR THIS PATENT
AN
       2006:205843 USPAT2
ΤI
       Method for producing single crystal and
       single crystal
IN
       Mitamura, Nobuaki, Fukushima, JAPAN
       Ohta, Tomohiko, Gunma, JAPAN
       Fusegawa, Izumi, Fukushima, JAPAN
       Sakurada, Masahiro, Fukushima, JARAN
       Ozaki, Atsushi, Fukushima, JAPAN
       Shin-Etsu Handotai Co., Ltd., Tokyo, JAPAN (non-U.S. corporation) US 7226507 B2 20070605
PA
PΤ
       WO 2005001169 20050106
       US 2004-561865
AΤ
                                 20040527
       WO 2004-JP7252
                                 20040527
                                 20060220
                                           PCT 371 date
PRAI
       JP 2003-184838
                            20030627
DT
       Utility
FS
       GRANTED
EXNAM
       Primary Examiner: Hiteshew, Felisa
LREP
       Oliff & Berridge PLC
CLMN
       Number of Claims: 9
ECL
       Exemplary Claim: 1
DRWN
       12 Drawing Figure(s); 9 Drawing Page(s)
LN.CNT 995
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 9 OF 10 USPAT2 on STN
\Gamma8
AΒ
       There are disclosed a silicon waffer for epitaxial growth wherein the
       wafer is produced by slicing a s_i^{\dagger}licon single crystal
       grown with doping nitrogen according to the Czochralski method (
       CZ method) in the region where at least the center of the wafer
       becomes V region in which the void type defects are generated, and
       wherein the number of defects having an opening size of 20 nm or less
       among the void type defects appearing on the surface of the wafer is
       0.02/cm.sup.2 or less, and an editalial wafer wherein an epitaxial layer
       is formed on the silicon wafer for epitaxial growth. Thereby, there can
       be produced an epitaxial wafer having a high gettering capability
       wherein very few SF exist in the epitaxial layer easily at high
       productivity and at low cost.
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
ΑN
       2005:243977 USPAT2
ΤI
       Silicon wafer for epitaxial growth, an epitaxial wafer, and a method for
       producing it
ΙN
       Hoshi, Ryoji, Fukushima, JAPAN
       Sonokawa, Susumu, Fukushima, JAHAN
PΑ
       Shin-Etsu Handotai Co., Ltd., Tdkyo, JAPAN (non-U.S. corporation)
PΙ
       US 7204881
                            B2 20070417
       WO 2001027362 20010419
AΙ
       US 2003-520099
                                20030708 (10)
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defect-free region with pulling the single crystal

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WO 2003-JP8671
                                  20030708
                                  20050104
                                             CT 371 date
PRAI
        JP 2002-204703
                             20020712
DT
       Utility
FS
       GRANTED
       Primary Examiner: Hiteshew, Felisa
EXNAM
LREP
       Oliff & Berridge, PLC
       Number of Claims: 29
CLMN
ECL
       Exemplary Claim: 1
DRWN
       10 Drawing Figure(s); 6 Drawing Page(s)
LN.CNT 845
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L8
     ANSWER 10 OF 10 USPAT2 on STN
ΑB
        The present invention provides a silicon wafer sliced from a silicon
        single crystal ingot grown by the Czochralski method
       under such conditions that V-rich region should become dominant, wherein
       count number of particles having a size of 0.1 \mu m or more is 1
       count/cm.sup.2 or less when particles are counted by using a particle
       counter and a method for producing a silicon single
       crystal. Thus, there is provided a production technique that can
       improve productivity and reduce cost for high quality silicon wafers of excellent device characteristics by further reducing density and size of
       defects such as COP.
CAS INDEXING IS AVAILABLE FOR THIS PATENT
ΑN
       2002:284777 USPAT2
ΤI
       Silicon wafer and method for producing silicon single
       crystal ·
IN
       Hoshi, Ryoji, Fukushima, JAPAN
       Fusegawa, Izumi, Fukushima, JAPAN
       Ohta, Tomohiko, Fukushima, JAPAN
       Maeda, Shigemaru, Fukushima, JAPAN
       Shin-Etsu Handotai Co., Ltd., Tokyo, JAPAN (non-U.S. corporation) US 6632411 B2 20031014
PA
PΙ
       WO 2001073169 20011004
       US 2001-979519
ΑI
                                  20011123
                                           (9)
       WO 2001-JP2451
                                 20010327
PRAI
       JP 2000-92337
                             20000329
DT
       Utility
FS
       GRANTED
EXNAM
       Primary Examiner: Hiteshew, Felisa
CLMN
       Number of Claims: 20
ECL
       Exemplary Claim: 1
DRWN
       7 Drawing Figure(s); 4 Drawing Page(s)
LN.CNT 723
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
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# PALM INTRANET

Day: Tuesday Date: 6/5/2007 Time: 14:29:34

### **Inventor Name Search Result**

Your Search was:

Last Name = FUSEGAWA

First Name = IZUMI

Application#	Patent#	Status	Date Filed	Title	Inventor Name		
06941624	Not Issued	161	12/11/1986	METHOD AND APPARATUS FOR CZOCHRALSKI SINGLE CRYSTAL GROWING	FUSEGAWA, IZUMI		
07242414	4956153	250	09/09/1988	APPARATUS FOR CZOCHRALSKI SINGLE CRYSTAL GROWING	FUSEGAWA, IZUMI		
<u>07496750</u>	5110404	150	03/21/1990	METHOD FOR HEAT PROCESSING OF SILICON	FUSEGAWA, IZUMI		
07703750	Not Issued	166	05/21/1991	METHOD FOR PULLING UP SEMICONDUCTOR SINGLE CRYSTAL	FUSEGAWA, IZUMI		
07713848	5306387	150	06/12/1991	METHOD FOR PULLING UP SEMICONDUCTOR SINGLE CRYSTAL	FUSEGAWA, IZUMI		
07729026	Not Issued	161	07/12/1991	METHOD FOR PULLING SEMICONDUCTOR SINGLE CRYSTAL	FUSEGAWA, IZUMI		
07796385	5688319	150	11/22/1991	METHOD FOR TESTING ELECTRICAL PROPERTIES OF SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI		
<u>07850506</u>	5262338	250	03/13/1992	METHOD FOR FABRICATION OF SEMICONDUCTOR DEVICE	FUSEGAWA, IZUMI		
<u>07850915</u>	Not Issued	166	03/13/1992	HEAT TREATMENT OF SI SINGLE CRYSTAL	FUSEGAWA, IZUMI		
07850916	5386796	150		METHOD FOR TESTING QUALITY OF SILICON WAFER	FUSEGAWA, IZUMI		
07852612	5248378	150	03/17/1992	METHOD AND APPARATUS FOR PRODUCING SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI		
07953918	5359959	250	09/30/1992	METHOD FOR PULLING UP	FUSEGAWA, IZUMI		

				SEMI-CONDUCTOR SINGLE CRYSTAL	
<u>07961182</u>	5462010	250	10/14/1992	APPARATUS FOR SUPPLYING GRANULAR RAW MATERIAL FOR A SEMICONDUCTOR SINGLE CRYSTAL PULLING APPARATUS	FUSEGAWA, IZUMI
07961764	5373805	250	10/15/1992	SINGLE CRYSTAL PULLING APPARATUS	FUSEGAWA, IZUMI
08011744	5340434	250	02/01/1993	PROCESS FOR PRODUCING SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI
08012172	5361721	250	02/02/1993	SINGLE CRYSTAL PULLING APPARATUS	FUSEGAWA, IZUMI
08108285	Not Issued	166	08/19/1993	HEAT TREATMENT OF SI SINGLE CRYSTAL	FUSEGAWA, IZUMI
08190604	Not Issued	166	02/02/1994	CRUCIBLE FOR PULLING SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI
08238722	5534112	150	05/05/1994	METHOD FOR TESTING ELECTRICAL PROPERTIES OF SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI
08293214	Not Issued	166	08/19/1994	APPARATU\$ FOR PRODUCING SILICON SINGLE CRYSTAL GROWN BY CZOCHRALSKI METHOD	FUSEGAWA, IZUMI
08395837	5501172	150	02/28/1995	METHOD OF GROWING SILICON SINGLE CRYSTALS	FUSEGAWA, IZUMI
08445029	Not Issued	166		HEAT TREATMENT OF SI SINGLE CRYSTAL	FUSEGAWA, IZUMI
08510436	5720809	250	08/02/1995	CRUCIBLE FOR PULLING SILICON SINGLE CRYSTAL .	FUSEGAWA, IZUMI
<u>08552164</u>	Not Issued	166	11/02/1995	APPARATUS FOR PRODUCING SILICON SINGLE CRYSTAL GROWN BY CZOCHRALSKI METHOD	FUSEGAWA, IZUMI
08699719	5725661	250	07/01/1996	EQUIPMENT FOR PRODUCING SILICON SINGLE CRYSTALS	FUSEGAWA, IZUMI
08754784	5938841	150	11/21/1996	DEVICE FOR PRODUCING SINGLE CRYSTAL	FUSEGAWA, IZUMI
08760959	5766346			APPARATÚS FOR PRODUCING SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI
08770499	5851283	150	12/20/1996	METHOD AND APPARATUS	FUSEGAWA, IZUMI

				FOR PRODUCTION OF SINGLE CRYSTAL	
08773351	5871583	150	12/26/1996	AN APPARATUS FOR PRODUCING SILICON CRYSTAL	FUSEGAWA, IZUMI
08916291	5834322	250	08/22/1997	HEAT TREATMENT OF SI SINGLE CRYSTAL	FUSEGAWA, IZUMI
09270277	6153009	150	03/16/1999	METHOD FOR PRODUCING A SILICON SINGLE CRYSTAL AND THE SILICON SINGLE CRYSTAL/PRODUCED THEREBY	FUSEGAWA, IZUMI
09290261	6117231	150	04/13/1999	METHOD OF MANUFACTURING SEMICONDUCTOR SILICON SINGLE CRYSTAL WAFER	FUSEGAWA, IZUMI
09429343	6387466	150	10/28/1999	SINGLE-CRYSTAL SILICON WAFER	FUSEGAWA, IZUMI
09646713	6565822	150	09/21/2000	EPITAXIAL SILICON WAFER, METHOD FOR PRODUCING THE SAME AND SUBTRATE FOR EPITAXIAL SILICON WAFER	FUSEGAWA, IZUMI
<u>09673480</u>	Not	161	10/16/2000	Method for producing silicon	FUSEGAWA, IZUMI
	Issued		<u></u>	single crystals	
09674858	1ssued 6423285	150	11/07/2000	Method for producing silicon single crystal and production apparatus therefor as well as crystal and silicon wafer produced by the method	FUSEGAWA, IZUMI
09674858		-		Method for producing silicon single crystal and production apparatus therefor as well as crystal and silicon wafer	
	6423285	150	09/21/2001	Method for producing silicon single crystal and production apparatus therefor as well as crystal and silicon wafer produced by the method  SINGLE CRYSTAL GROWING	
09937132	6423285 6632280 6592662	150	09/21/2001 10/24/2001 11/23/2001	Method for producing silicon single crystal and production apparatus therefor as well as crystal and silicon wafer produced by the method  SINGLE CRYSTAL GROWING DEVICE  METHOD FOR PREPARING SILICON SINGLE CRYSTAL AND SILICON SINGLE	FUSEGAWA, IZUMI
<u>09937132</u> <u>09959381</u>	6423285 6632280 6592662	150 150	09/21/2001 10/24/2001 11/23/2001	Method for producing silicon single crystal and production apparatus therefor as well as crystal and silicon wafer produced by the method  SINGLE CRYSTAL GROWING DEVICE  METHOD FOR PREPARING SILICON SINGLE CRYSTAL AND SILICON SINGLE CRYSTAL AND SILICON SINGLE CRYSTAL  SILICON WAFER AND METHOD FOR PRODUCING SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI FUSEGAWA, IZUMI

B.			u		61
				SINGLE CRYSTAL	
10312921	6893499	150	12/26/2002	SILICON SINGLE CRYSTAL WAFER AND METHOD FOR MANUFACTURING THE SAME	FUSEGAWA, IZUMI
10500580	7129123	150	07/01/2004	AN SOI WAFER AND A METHOD FOR PRODUCING AN SOI WAFER	FUSEGAWA, IZUMI
<u>√10510695</u>	7179330	150	10/08/2004	METHOD OF MANUFACTURING SILICON SINGLE CRYSTAL, SILICON SINGLE CRYSTAL AND SILICON WAFER	FUSEGAWA, IZUMI
10512470	Not Issued	90	10/26/2004	A SILICON SINGLE CRYSTAL WAFER, AN EPITAXIAL WAFER AND A METHOD FOR PRODUCING A SILICON SINGLE CRYSTAL	FUSEGAWA, IZUMI
10516347	Not . Issued	94	11/30/2004	GRAPHITE HEATER FOR PRODUCING SINGLE CRYSTAL, APPARATUS FOR PRODUCING SINGLE CRYSTAL, AND METHOD FOR PRODUCING SINGLE CRYSTAL	FUSEGAWA, IZUMI
10538878	7214268	150	06/14/2005	METHOD OF PRODUCING P- DOPED SILICON SINGLE CRYSTAL AND P-DOPED N- TYPE SILICON SINGLE CRYSTAL WAFER	FUSEGAWA, IZUMI
10542376	Not Issued	30	07/14/2005	AN SOI WAFER AND A METHOD FOR PRODUCING THE SAME	FUSEGAWA, IZUMI
10561865	7226507	150	02/20/2006	METHOD FOR PRODUCING SINGLE CRYSTAL AND SINGLE CRYSTAL	FUSEGAWA, IZUMI
10568186	Not Issued <b>Aplica</b>			Method for producing a single crystal and silicon single crystal wafer	FUSEGAWA, IZUMI

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### **Inventor Name Search Result**

Your Search was:

Last Name = MITAMURA First Name = NOBUAKI

	Application# Patent# Status Date Filed Title Inventor Name							
	Patent#	Status	Date Filed	Title	Inventor Name			
07557574	5030017		07/24/1990	ROLLING BEARING	MITAMURA, NOBUAKI			
07560445	5084116	150	07/31/1990	ROLLING CONTACT ELEMENT STEEL AND ROLLING BEARING MADE THEREOF	MITAMURA, NOBUAKI			
07572480	5085733	150	08/23/1990	ROLLING CONTACT PARTS STEEL AND ROLLING BEARING MADE THEREOF	MITAMURA, NOBUAKI			
07915503	Not Issued	161		BALL AND ROLLER BEARING	MITAMURA, NOBUAKI			
07946638	5338377	150	09/18/1992	BALL-AND/ROLLER BEARING /	MITAMURA, NOBUAKI			
08134588	5427457	150	10/12/1993	ROLLING BEARING	MITAMURA, NOBUAKI			
08242668	5413643	150	05/13/1994	ROLLING BEARING	MITAMURA, NOBUAKI			
08374179	Not Issued	166	01/18/1995	TOROIDAL/TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI			
· <u>08512419</u>	5660647	150	08/08/1995	ROLLING BEARING WITH IMPROVED WEAR RESISTANCE	MITAMURA, NOBUAKI			
08519643	5626974	150		ROLLING BEARING FOR USE UNDER HIGH TEMPERATURE CONDITIONS				
08536773	5672014	150	09/29/1995	ROLLING BEARINGS	MITAMURA, NOBUAKI			
08542828	5853660		10/13/1995	A ROLLING BEARING MADE OF IMPROYED BEARING STEEL	MITAMURA, NOBUAKI			
08683195	5958155	150		PROCESS FOR PRODUCING THIN FILM	MITAMURA, NOBUAKI			
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08745635	5855531	150	11/08/1996	COMPONENT PARTS OF A TOROIDAL-TYPE CONTINUOUSLY VARIABLE TRANSMISSION HAVING IMPROVED LIFE	MITAMURA, NOBUAKI
08763883	5887015	150	12/11/1996	HEATER MECHANISM FOR CRYSTAL PULLING APPARATUS	MITAMURA, NOBUAKI
08877950	5989694	150	06/17/1997	ROLLING BEARING	MITAMURA, NOBUAKI
08955294	Not Issued	164	10/21/1997	ROLLING BEARING MADE OF IMPROVED BEARING STEEL	MITAMURA, NOBUAKI
09098980	6171414	150	06/17/1998	ROLLING BEARING	MITAMURA, NOBUAKI
09108174	6174257			TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09181911	6174258	150	10/29/1998	TOROIDAL-TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09183630	6066068	150	10/30/1998	TOROIDAL ITYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09187607	6165100	150	11/06/1998	HIGH-CLEANNESS STEEL AND TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION INCLUDING COMPONENTS SUCH AS INPUT/OUTPUT DISCS, POWER ROLLER AND CAM DISC USING THE HIGH- CLEANNESS STEEL	MITAMURA, NOBUAKI
09226032	6174085	150	11	LINEAR/GUIDE BEARING DEVICE	MITAMURA, NOBUAKI
09235052	6196946	150		POWER ROLLER BEARING OF TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION AND METHOD OF MANUFACTURING POWER ROLLER BEARING OF TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09245931	Not	161	02/08/1999	TEMPERATURE-	MITAMURA,

	Issued			INDEPENDENT OPTICAL ELEMENT	NOBUAKI
09272731	6210542	150	11/04/1998	PROCESS FOR PRODUCING THIN FILM, THIN FILM AND OPTICAL INSTRUMENT INCLUDING THE SAME	MITAMURA, NOBUAKI
09339238	6332714	150	06/24/1999	INDUCTION-HARDENED ROLLING BEARING DEVICE	MITAMURA, NOBUAKI
09344380	6328669	150	06/25/1999	TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09349204	6176806	150	07/07/1999	CAM DISK FOR TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09358554	6478894	150	07/22/1999	ROLLING BEARING	MITAMURA, NOBUAKI
09379748	6152605	150	08/24/1999	BALL BEARING	MITAMURA, NOBUAKI
<u>09401917</u>	6358440	150	09/23/1999	PROCESS FOR PRODUCING THIN FILM, THIN FILM AND OPTICAL INSTRUMENT INCLUDING THE SAME	MITAMURA, NOBUAKI
<u>09697179</u>	6829053	150	10/27/2000	AIRGAP TYPE ETALON AND APPARATUS UTILIZING THE SAME	MITAMURA, NOBUAKI
09886122	6413188	150	06/22/2001	TOROIDAL TYPE CONTINUOUSLY VARIABLE TRANSMISSION	MITAMURA, NOBUAKI
09939566	6646805	150	08/28/2001	APPARATUS FOR VARIABLE WAVELENGTH DISPERSION AND WAVELENGTH DISPERSION SLOPE	MITAMURA, NOBUAKI
09957413	6426022	150	09/20/2001	PROCESS FOR PRODUCING THIN FILM, THIN FILM AND OPTICAL INSTRUMENT INCLUDING THE SAME	MITAMURA, NOBUAKI
09984396	6807335	150	10/30/2001	WAVELENGTH CHARACTERISTIC VARIABLE APPARATUS	MITAMURA, NOBUAKI
10061307	6826318	150	02/04/2002	VARIABLE POLARIZATION PLANE ROTATOR AND OPTICAL DEVICE USING SAME	MITAMURA, NOBUAKI
10164438	6900940	150	06/10/2002	OPTICAL APPARATUS AND DEVICE	MITAMURA, NOBUAKI

10278868	7200297	150	10/24/2002	DEVICE USING A VIRTUALLY IMAGED PHASED ARRAY (VIPA) WITH AN IMPROVED TRANSMISSION WAVE CHARACTERISTIC OF OUTPUT LIGHT	MITAMURA, NOBUAKI
10286779	6862126	150	11/04/2002	TRANSMISSION WAVELENGTH CHARACTERISTICS VARIABLE OPTICAL ELEMENT, AND WAVELENGTH CHARACTERISTICS VARIABLE APPARATUS, OPTICAL AMPLIFIER, OPTICAL TRANSMISSION SYSTEM, AND CONTROL METHOD OF TRANSMISSION WAVELENGTH CHARACTERISTICS, USING SAME	MITAMURA, NOBUAKI
10310900	7137741	150	12/06/2002		MITAMURA, NOBUAKI
10340842	6909537	150	01/13/2003	DISPERSION COMPENSATOR WHOSE TRANSMISSION BAND IS FLATTENED	MITAMURA, NOBUAKI
10341380	6807008	150	01/14/2003	WAVELENGTH DISPERSION GENERATION APPARATUS, MULTI-FACED MIRROR USED FOR WAVELENGTH DISPERSION GENERATION APPARATUS, AND METHOD FOR MANUFACTURING THEREOF	MITAMURA, NOBUAKI
10351376	7016096	150	01/27/2003	TRANSMISSION WAVELENGTH CHARACTERISTICS VARIABLE OPTICAL ELEMENT, AND WAVELENGTH CHARACTERISTICS VARIABLE APPARATUS, OPTICAL AMPLIFIER, AND OPTICAL TRANSMISSION SYSTEM, USING SAME	MITAMURA, NOBUAKI
10410342	7037386	150	04/10/2003		MITAMURA, NOBUAKI

				TRANSMISSION	
10414308	6923576	150	04/16/2003	1	MITAMURA, NOBUAKI
10500580	7129123	150			MITAMURA, NOBUAKI
10510695	7179330	150		METHOD OF MANUFACTURING SILICON SINGLE CRYSTAL, SILICON SINGLE CRYSTAL AND SILICON WAFER	MITAMURA, NOBUAKI
10512470	Not Issued	90		A SILICON SINGLE CRYSTAL WAFER, AN EPITAXIAL WAFER AND A METHOD FOR PRODUCING A SILICON SINGLE CRYSTAL	MITAMURA, NOBUAKI

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#### **Inventor Name Search Result**

Your Search was:

Last Name = YANAGIMACHI

First Name = TAKAHIRO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08759223	<u>5888298</u>	150		MEMBER-HANDLING MECHANISM, AND MEMBER-HANDLING JIG FOR A CRYSTAL PULLING APPARATUS	YANAGIMACHI, TAKAHIRO
10204278	<u>6764548</u>	150			YANAGIMACHI, TAKAHIRO
<b>*</b> 1056818 <b>6</b>	Not Issued			Method for producing a single crystal and silicon single crystal wafer	YANAGIMACHI, TAKAHIRO

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	Yanagimachi	Takahiro	Search

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